

AMENDMENTS TO THE SPECIFICATION

In the Specification

Please replace paragraph [0048] beginning on page 17 with the following amended paragraph:

[0048] Alternatively, rather than such a negative acting chemically amplified resist, the resist may be any other type of resist including a physicochemical imaging mechanism that is thermally modifiable post exposure by a non-uniform thermal interaction with the layer portions. For example, the resist may be a negative acting resist, a positive ~~[[activating]]~~ acting resist, a chemically amplified resist, or other resists and may be based on a variety of imaging mechanisms including deprotection, depolymerization, rearrangement, intramolecular dehydration, condensation, cationic polymerization, and others.

Please replace paragraph [0081] beginning on page 32 with the following amended paragraph:

[0081] According to one embodiment, each of the spacing systems 1422, 1424, 1426, and 1428 comprise a spacer 1452, 1454, 1456, and 1458 that respectively may extend above a functional top surface ~~[[1432, 1434, 1436, and 1438]]~~ 1442, 1444, 1446, and 1448. The top surfaces ~~[[1432-1338]]~~ 1432-1438 may be substantially coplanar with a top functional surface of the source 1410, or they may be elevated or de-elevated with respect to the top surface of the source 1410, as desired. The spacers ~~[[1452-1358]]~~ 1452-1458 may provide a thermal energy gradient, such as described for the systems 700 and/or 800.

Please replace paragraph [0082] beginning on page 32 with the following amended paragraph:

[0082] According to one embodiment, the spacers ~~[[1452-1358]]~~ 1452-1458 are adjustable. For example, the spacer 1452 may be a screw spacer 1452B that is adjustable by rotation. In this embodiment, the solid 1432 may comprise a cylindrical void (not shown) that may open through a circular opening in the surface 1442. The void may or may not extend and open on a bottom surface of the solid 1432. The cylindrical void may comprise structure corresponding to a thread and shaft of the screw spacer 1452B. The spacer 1452 may also comprise a thermal insulator, such as a polyamide o-ring 1460. Such a system 1422 incorporating the spacer 1452B may be used by removing the solid 1432 from the void 1412, accurately adjusting the spacer 1452B with a screwdriver so that the spacer 1452B provides a desired distance relative to a top functional surface of the source 1410, accurately measuring the desired distance if desired, and replacing the solid 1432 back into the void 1412 prior to use.

Please replace paragraph [0083] beginning on page 32 with the following amended paragraph:

[0083] Alternatively, rather than adjustable spacing systems ~~[[1422-1328]]~~ 1422-1428, the systems 1422-1328 may be predetermined spacing systems that are not adjustable. In this embodiment, a plurality of such predetermined systems may be provided to be useful for different magnitudes and types of CD error reduction, so that one may be selected and used without adjustment.